

REMARKS

Upon entry of the amendment, claims 1-14 and 17-24 will be all the claims pending in the application. Claim 1 has been amended to incorporate the subject matter of claim 16, which has been canceled and further based on, for example, page 11, lines 3-8 of the specification. Claim 15 has been canceled.

Applicants respectfully submit that with the entry of the proposed amendments, the present application will be in condition for allowance. Accordingly, entry of the above amendments is respectfully requested.

Claims 1, 2, 4-14 and 17-23 are rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Ito et al. (US 4,690,856) in view of Ohmae et al. (US 5,047,479) and Saito et al. (US 4,429,076).

In addition, claim 3 is rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Ito et al. (US 4,690,856) in view of Ohmae et al. (US 5,047,479) and Saito et al. (US 4,429,076), and further in view of Applicants' alleged admissions.

Further, claims 15 and 16 are rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Ito et al. (US 4,690,856) in view of Ohmae et al. (US 5,047,479) and Saito et al. (US 4,429,076).

Applicants respectfully traverse the rejections.

Claim 1 is directed to a metal laminate comprising between two outer metal sheets an adhesive polymer layer, characterized in that the adhesive polymer layer comprises polyamide, a copolymer of ethylene and an unsaturated carboxylic acid and/or a derivative thereof and a reactive copolymer, comprising a styrene-maleic acid anhydride copolymer having a molecular weight of 1,400 to 50,000.

It is submitted that none of the cited art teaches nor suggests a metal laminate comprising a styrene-maleic acid anhydride copolymer having a molecular weight of 1,400 to 50,000. In addition, none of the cited art teaches or suggests the advantages related thereto as emphasized by the claimed metal laminate. That is, the claimed metal laminate exhibits very good adhesion properties along with excellent tensile modulus, even at elevated temperatures, and thermal stability. *See* page 10, lines 20-23 and Example 2 of the specification.

Thus, for at least the foregoing reasons, it is respectfully submitted that claim 1 is patentable over the cited art.

Further, claims 2-14 and 17-24 depend, directly or indirectly, from claim 1, and thus it is respectfully submitted that these claims are patentable for at least the same reasons as claim 1.

In view of the above, withdrawal of the rejections is respectfully requested.

Reconsideration and allowance of claims 2-14 and 17-24 is respectfully requested.

If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below. The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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